

The experts look ahead

Cramming more components onto integrated circuits

With unit cost falling as the number of components per circuit rises, by 1975 economics may dictate squeezing as many as 65,000 components on a single silicon chip

By Gordon E. Moore

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The future of integrated electronics is the future of electronics itself. The advantages of integration will bring about a proliferation of electronics, pushing this science into many new areas.

Integrated circuits will lead to such wonders as home computers—or at least terminals connected to a central computer—automatic controls for automobiles, and personal portable communications equipment. The electronic wrist-watch needs only a display to be feasible today.

But the biggest potential lies in the production of large systems. In telephone communications, integrated circuits in digital filters will separate channels on multiplex equipment. Integrated circuits will also switch telephone circuits and perform data processing.

Computers will be more powerful, and will be organized in completely different ways. For example, memories built of integrated electronics may be distributed throughout the

machine instead of being concentrated in a central unit. In addition, the improved reliability made possible by integrated circuits will allow the construction of larger processing units. Machines similar to those in existence today will be built at lower costs and with faster turn-around.

Present and future

By integrated electronics, I mean all the various technologies which are referred to as microelectronics today as well as any additional ones that result in electronics functions supplied to the user as irreducible units. These technologies were first investigated in the late 1950's. The object was to miniaturize electronics equipment to include increasingly complex electronic functions in limited space with minimum weight. Several approaches evolved, including microassembly techniques for individual components, thin-film structures and semiconductor integrated circuits.

Each approach evolved rapidly and converged so that each borrowed techniques from another. Many researchers believe the way of the future to be a combination of the various approaches.

The advocates of semiconductor integrated circuitry are already using the improved characteristics of thin-film resistors by applying such films directly to an active semiconductor substrate. Those advocating a technology based upon films are developing sophisticated techniques for the attachment of active semiconductor devices to the passive film arrays.

Both approaches have worked well and are being used in equipment today.

The author

Dr. Gordon E. Moore is one of the new breed of electronic engineers, schooled in the physical sciences rather than in electronics. He earned a B.S. degree in chemistry from the University of California and a Ph.D. degree in physical chemistry from the California Institute of Technology. He was one of the founders of Fairchild Semiconductor and has been director of the research and development laboratories since 1959.